



JMSH1004BC
JMSH1004BE

100V 3.7mΩ N-Ch Power MOSFET

Features

- Ultra-low $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100% R_g Tested
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant

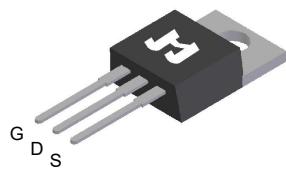
Product Summary

Parameter	Value	Unit
V_{DS}	100	V
$V_{GS(th)}\text{ Typ}$	2.7	V
$I_D (@ V_{GS} = 10V)$ ⁽¹⁾	134	A
$R_{DS(ON)}\text{ Typ} (@ V_{GS} = 10V)$	3.7	mΩ

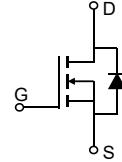
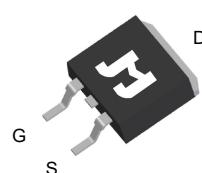
Applications

- Power Management in Computing, CE, IE 4.0, Communications
- Motor Driving in Power Tool, E-vehicle, Robotics
- Current Switching in DC/DC & AC/DC (SR) Sub-systems

TO-220-3L Top View



TO-263-3L Top View



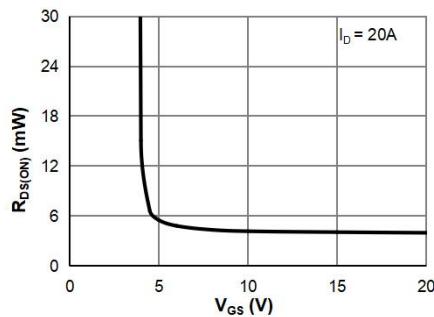
Ordering Information

Device	Package	# of Pins	Marking	MSL	T_J (°C)	Media	Quantity (pcs)
JMSH1004BC-U	TO-220-3L	3	SH1004B	N/A	-55 to 150	Tube	50
JMSH1004BE-13	TO-263-3L	3	SH1004B	3	-55 to 150	13-inch Reel	800

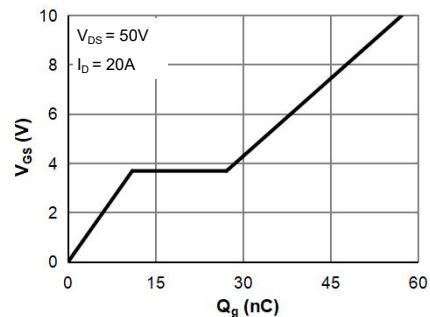
Absolute Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	100	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ⁽¹⁾	I_D	134	A
		85	
Pulsed Drain Current ⁽²⁾	I_{DM}	411	A
Avalanche Current ⁽³⁾	I_{AS}	45	A
Avalanche Energy ⁽³⁾	E_{AS}	304	mJ
Power Dissipation ⁽⁴⁾	P_D	156	W
		63	
Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

$R_{DS(ON)}$ vs. V_{GS}



Gate Charge





JMSH1004BC
JMSH1004BE

Electrical Characteristics (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

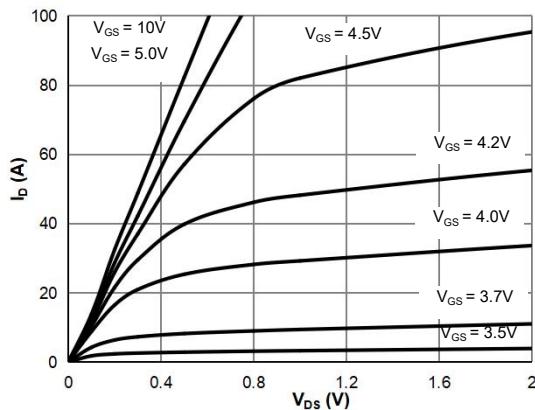
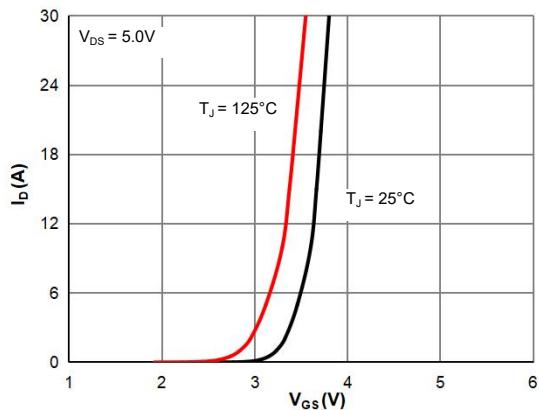
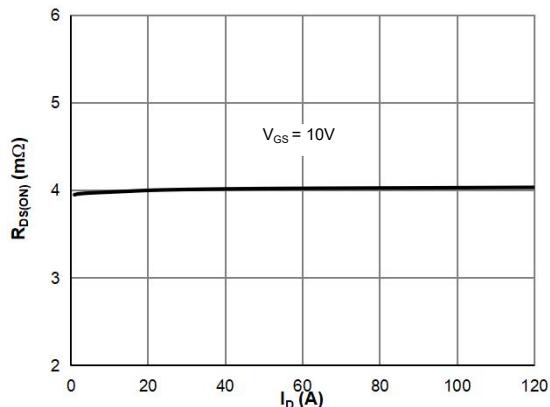
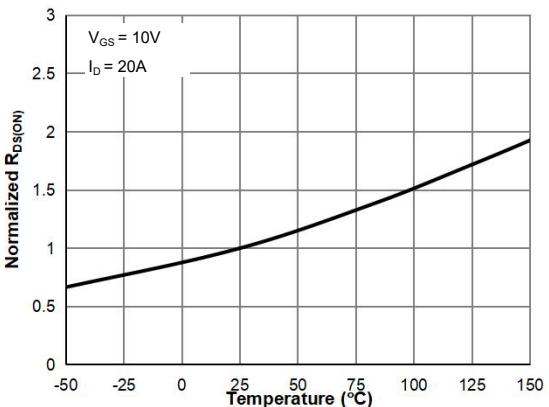
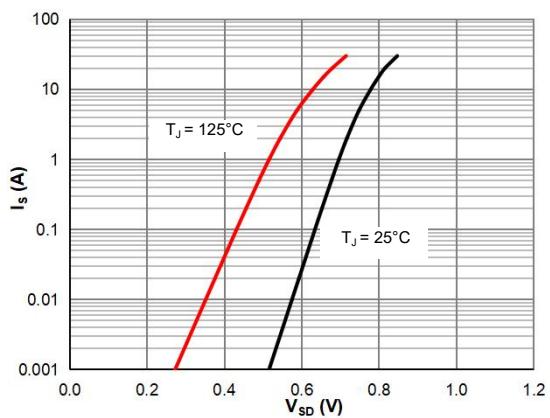
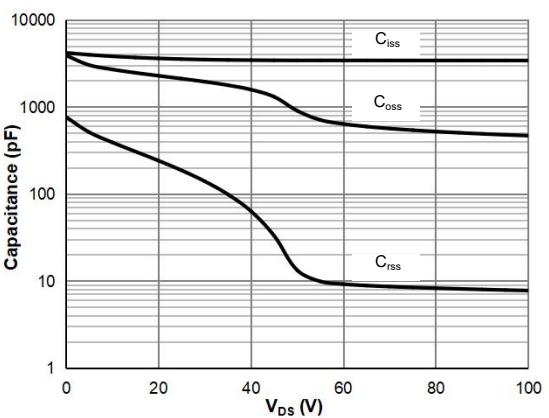
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DS}}$	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$			1.0	μA
		$T_J = 55^\circ\text{C}$			5.0	
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	2.7	4.0	V
Static Drain-Source ON-Resistance	$R_{DS(\text{ON})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	TO-263-3L	3.7	4.5	$\text{m}\Omega$
			TO-220-3L	3.9	4.7	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = 5\text{V}, I_D = 20\text{A}$		106		S
Diode Forward Voltage	V_{SD}	$I_S = 1\text{A}, V_{GS} = 0\text{V}$		0.71	1.0	V
Diode Continuous Current	I_S	$T_C = 25^\circ\text{C}$			156	A
DYNAMIC PARAMETERS⁽⁵⁾						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$		3433		pF
Output Capacitance	C_{oss}			905		pF
Reverse Transfer Capacitance	C_{rss}			13.0		pF
Gate Resistance	R_g	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$		2.1		Ω
SWITCHING PARAMETERS⁽⁵⁾						
Total Gate Charge (@ $V_{GS} = 10\text{V}$)	Q_g	$V_{GS} = 0$ to 10V $V_{DS} = 50\text{V}, I_D = 20\text{A}$		57		nC
Total Gate Charge (@ $V_{GS} = 6.0\text{V}$)	Q_g			38		nC
Gate Source Charge	Q_{gs}			11.0		nC
Gate Drain Charge	Q_{gd}			16.1		nC
Turn-On Delay Time	$t_{D(on)}$	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}$ $R_L = 2.5\Omega, R_{GEN} = 6\Omega$		14.1		ns
Turn-On Rise Time	t_r			34		ns
Turn-Off Fall Time	$t_{D(off)}$			60		ns
Turn-Off Fall Time	t_f			50		ns
Body Diode Reverse Recovery Time	t_{rr}		$I_F = 15\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	60		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = 15\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		63		nC

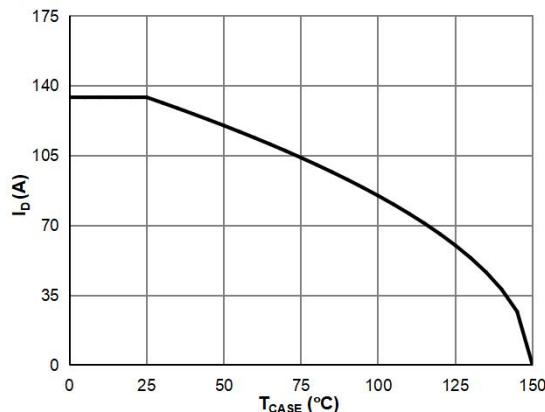
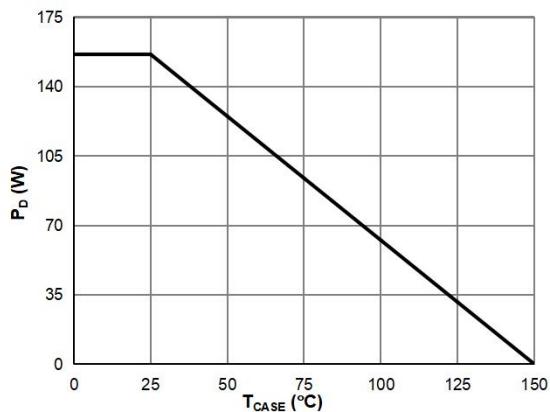
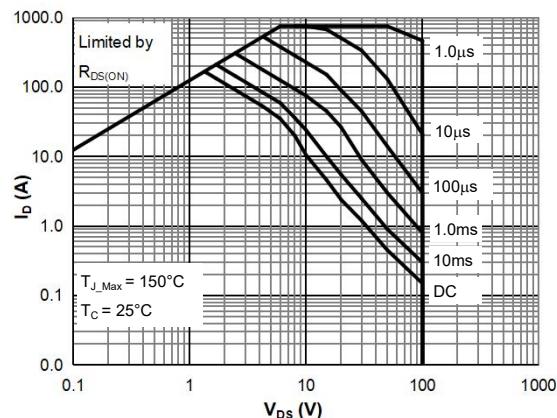
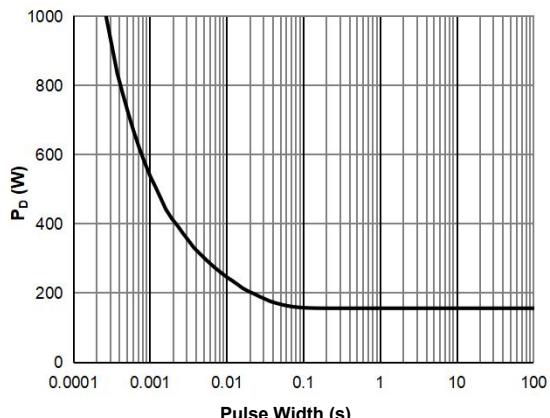
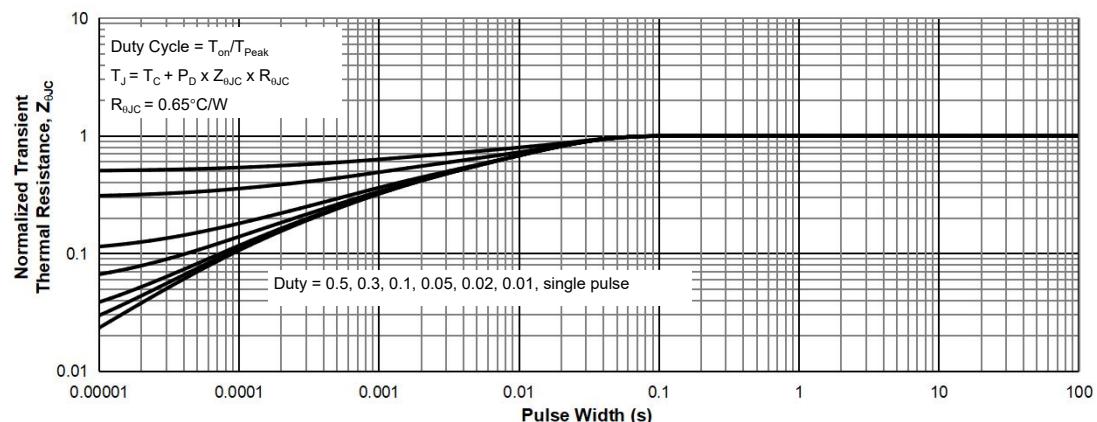
Thermal Performance

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	R_{JJA}	45	55	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	R_{JJC}	0.65	0.80	$^\circ\text{C/W}$

Notes:

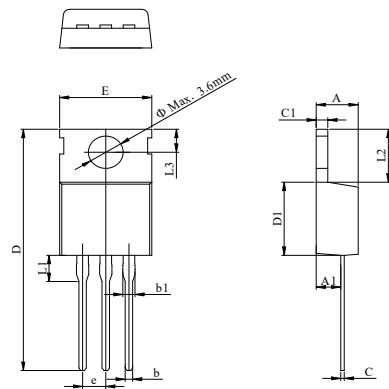
1. Computed continuous current assumes the condition of $T_{J_{\text{Max}}}$ while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under $T_{J_{\text{Max}}} = 150^\circ\text{C}$.
3. This single-pulse measurement was taken under the following condition [$L = 300\mu\text{H}, V_{GS} = 10\text{V}, V_{DS} = 50\text{V}$] while its value is limited by $T_{J_{\text{Max}}} = 150^\circ\text{C}$.
4. The power dissipation P_D is based on $T_{J_{\text{Max}}} = 150^\circ\text{C}$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical & Thermal Characteristics

Figure 1: Saturation Characteristics

Figure 2: Transfer Characteristics

Figure 3: $R_{DS(ON)}$ vs. Drain Current

Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

Figure 5: Body-Diode Characteristics

Figure 6: Capacitance Characteristics

Typical Electrical & Thermal Characteristics

Figure 7: Current De-rating

Figure 8: Power De-rating

Figure 9: Maximum Safe Operating Area

Figure 10: Single Pulse Power Rating, Junction-to-Case

Figure 11: Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information

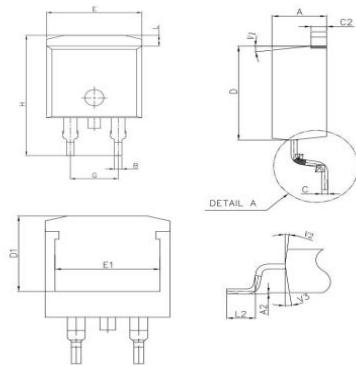
Package Outline



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.24		4.70
A1	2.20		3.00
b	0.70		0.95
b1	1.14		1.70
C	0.40		0.60
C1	1.15		1.40
D	28.00		29.80
D1	8.80		9.90
E	9.70		10.50
L1			3.80
L2	6.25		6.90
L3	2.40		3.00
e		2.54 BSC	

TO-263-3L Package Information

Package Outline



SYMBOL	DIMENSIONS		
	MIN	NOM	MAX
A	4.3	4.55	4.7
A2	0		0.25
B	0.75	0.8	0.85
C	0.38	0.46	0.55
C2	1.25	1.3	1.35
D	8.9	9.3	9.6
D1	7.4	7.65	7.9
E	9.9	10.05	10.21
E1	8.3	8.6	8.9
G	5.03	5.08	5.13
H	14.7	15	15.8
L2	2.2	2.35	2.5

Recommended Footprint

